

SEQUENTIAL STATION TOOL FOR WET PROCESSING OF SEMICONDUCTOR WAFERS

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ABSTRACT OF THE DISCLOSURE

Methods and apparatus are provided for processing semiconductor wafers sequentially. Sequential processes employ multi-station processing modules, where particular encompassing wafer processes are divided into sub-processes, each optimized
10 for increasing wafer to wafer uniformity, result quality, and overall wafer throughput. In one example, a copper electroplating module includes separate stations for wetting, initiation, seed layer repair, fill, overburden, reclaim, and rinse.

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